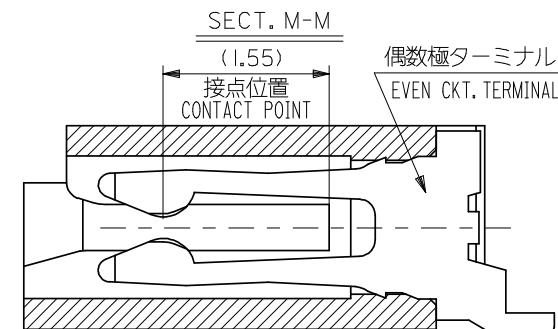
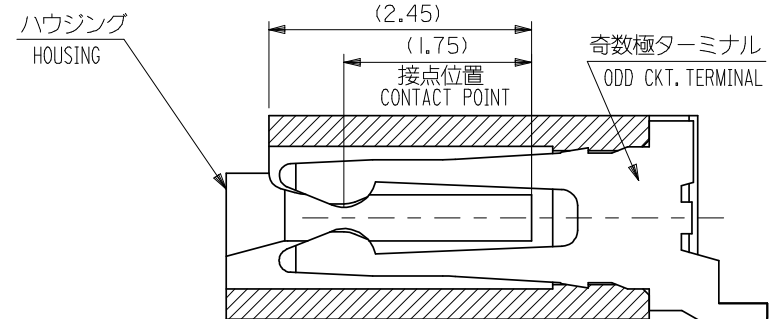
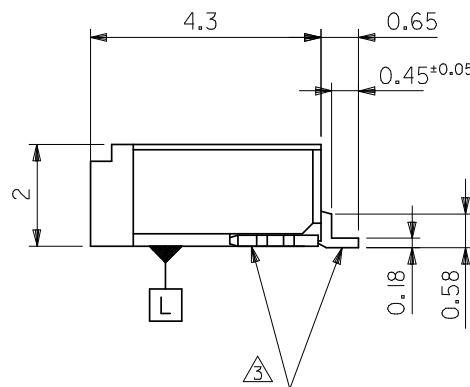
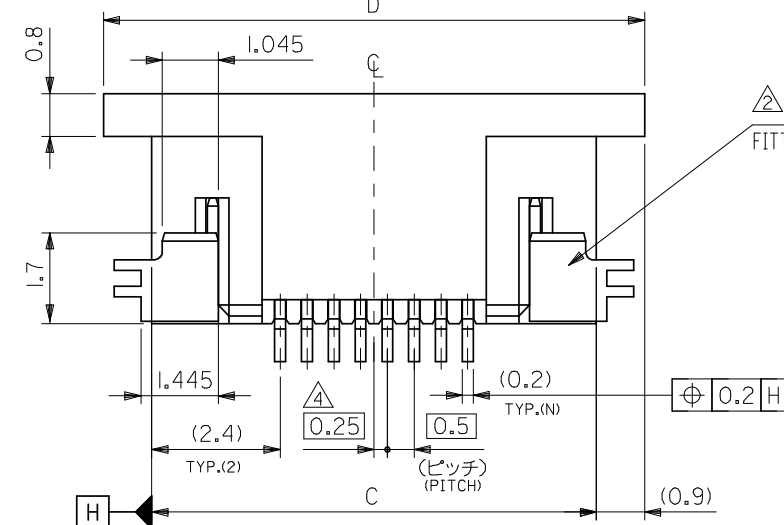




注記(NOTES)

1. 使用材料 (MATERIAL):
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE t±0.2
錫ビスマスメッキ 1. 0マイクロメートル以上
TIN-BISMUTH 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
ハウジング (HOUSING): 4-6 ナイロン (46 NYLON), UL 94V-0
金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE t±0.2
錫メッキ 1. 0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
② パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB, PATTERN.)
③ ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面  に対し上方向 0.1MAX. 下方向 0.15MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM 
④ UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
5. 本製品は 52689-***0 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***0.

REVISED EC NO: J2008-4308 DRWN: NABEI CH'KD: THARUYAMA APPR: NUKITA 2008/06/27 2008/06/30 2008/06/30	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY K. TOJO	DATE '04/02/03					
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE '04/02/03	molex MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2		SD-52689-034		1 OF 2		
B	REV	SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

F

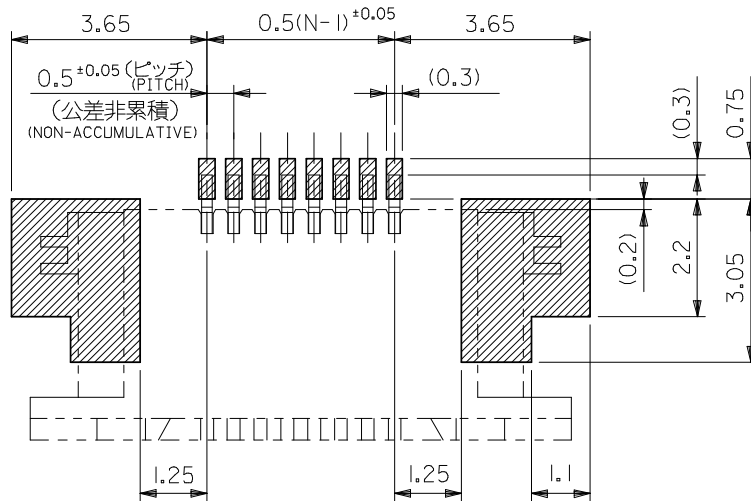
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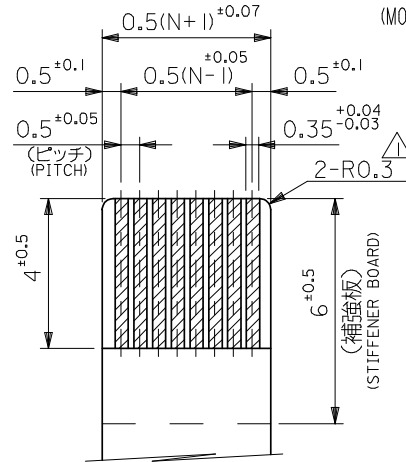
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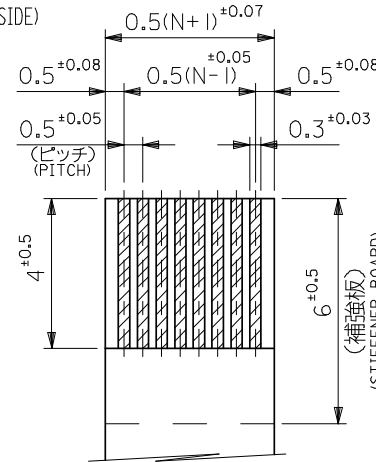
参考基板レイアウト
(マウント面)

REFERENCE P.C.BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合F P C推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合F F C推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

F P Cについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

- △ R0.3は、F P Cの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
17.1	20.6	18.8	15.0	14.0	-2987	-2949	29
16.6	20.1	18.3	14.5	13.5	-2887	-2849	28
16.1	19.6	17.8	14.0	13.0	-2787	-2749	27
15.6	19.1	17.3	13.5	12.5	-2687	-2649	26
15.1	18.6	16.8	13.0	12.0	-2587	-2549	25
14.6	18.1	16.3	12.5	11.5	-2487	-2449	24
14.1	17.6	15.8	12.0	11.0	-2387	-2349	23
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
13.1	16.6	14.8	11.0	10.0	-2187	-2149	21
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
12.1	15.6	13.8	10.0	9.0	-1987	-1949	19
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
9.6	13.1	11.3	7.5	6.5	-1487	-1449	14
9.1	12.6	10.8	7.0	6.0	-1387	-1349	13
8.6	12.1	10.3	6.5	5.5	-1287	-1249	12
8.1	11.6	9.8	6.0	5.0	-1187	-1149	11
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
7.1	10.6	8.8	5.0	4.0	-0987	-0949	9
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.6	9.1	7.3	3.5	2.5	-0687	-0649	6
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

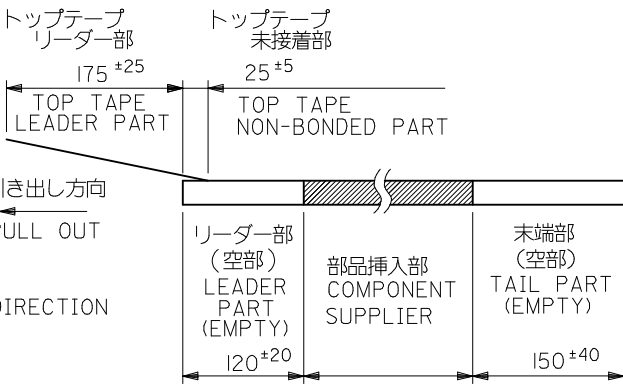
52689-***49
MODEL NO.

W D C B A
EMBOSSED TAPE
ORDER No. オーダー番号 MATERIAL NO. 極数 CKT.

REVISED EC NO: J2008-4308 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA REV B	DESCRIPTION 2008/06/27 2008/06/30 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/03					
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/02/03	MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52689-034		2 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

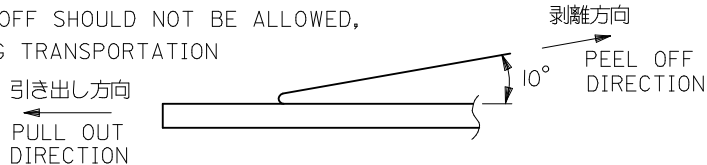
注記 NOTES

1. 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-034.
2. 梱包数量：1000個／リール
NUMBER OF CONNECTORS:1000PCS/REEL
3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)
0.1～1.3N {10～130gf}
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1～1.3N {10～130gf}(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



5. 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

6. 本製品は52689-**-93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-**-93.

7. FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フォルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM :POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

8. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED EC NO.: J2009-2061 DRWN:TKON CHKD:HMAJIMOTO APPR:MIKI ITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER		DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-				
		10 OVER 30 UNDER		CHECKED BY K. TOJO	DATE 2004/02/03					
		30 OVER		APPROVED BY M. SASAO	DATE 2004/02/03	MOLEX INCORPORATED				
		ANGULAR		MATERIAL NO.		DOCUMENT NO.				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2,3		SD-52689-035				
REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

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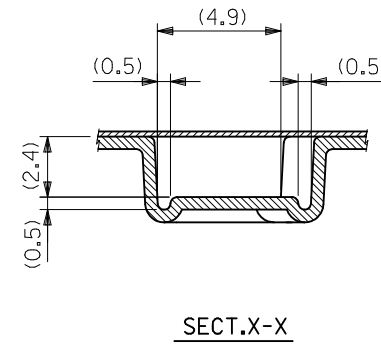
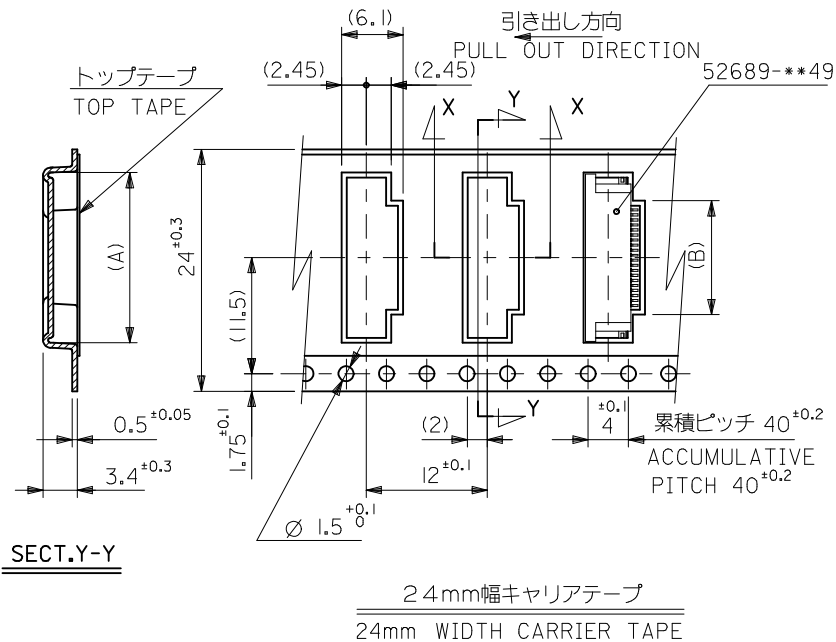
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24	29.4	25.4	11.8	17.4	52689-2287	22
52689-***87	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO.
MODEL NO.						極数 CIRCUIT

REVISED EC NO.: J2009-2061 DRAWN: I KON CHKD: H MATSUMOTO APPR: NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER		DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-				
		10 OVER 30 UNDER		CHECKED BY K. TOJO	DATE 2004/02/03					
		30 OVER		APPROVED BY M. SASAO	DATE 2004/02/03	MOLEX INCORPORATED				
		ANGULAR		MATERIAL NO.	DOCUMENT NO.					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52689-035				
REV A		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							